

Title (en)
PHOTOSENSITIVE COMPOSITION

Title (de)
LICHTEMPFLINDLICHE ZUSAMMENSETZUNG

Title (fr)
COMPOSITION PHOTOSENSIBLE

Publication
EP 1177478 A1 20020206 (EN)

Application
EP 00931115 A 20000504

Priority
• CH 89999 A 19990511
• EP 0004009 W 20000504

Abstract (en)
[origin: WO0068739A1] A photosensitive polymerisable composition, which comprises at least one cyclic and/or oligomeric compound composed of structural units of formula (I), wherein R is identical or different radicals of formula $-(A)-O-C(O)-C(R_1)=CH_2$, and R₁ is hydrogen or methyl, A is a transition group, and n is an integer from 3 to 18, preferably 3 or 4 and, most preferably, 3, and the use of this composition as photostructurable solder stopping resist for the production of solder masks for printed circuit boards.

IPC 1-7
G03F 7/027

IPC 8 full level
C08F 290/00 (2006.01); **C08G 79/04** (2006.01); **G03F 7/027** (2006.01); **H05K 3/28** (2006.01)

CPC (source: EP KR)
C08F 2/48 (2013.01 - KR); **C08F 2/50** (2013.01 - KR); **G03F 7/027** (2013.01 - EP KR); **G03F 7/029** (2013.01 - KR); **G03F 7/031** (2013.01 - KR); **G03F 7/033** (2013.01 - KR); **H05K 3/287** (2013.01 - EP)

Citation (search report)
See references of WO 0068739A1

Designated contracting state (EPC)
AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE

DOCDB simple family (publication)
WO 0068739 A1 20001116; AU 4916800 A 20001121; CA 2369025 A1 20001116; CN 1350660 A 20020522; EP 1177478 A1 20020206; HK 1044048 A1 20021004; JP 2002544542 A 20021224; KR 20020006698 A 20020124

DOCDB simple family (application)
EP 0004009 W 20000504; AU 4916800 A 20000504; CA 2369025 A 20000504; CN 00807369 A 20000504; EP 00931115 A 20000504; HK 02105574 A 20020729; JP 2000616465 A 20000504; KR 20017012695 A 20011005